

Title (en)
PRODUCTION METHOD FOR TRANSFER MOLD, TRANSFER MOLD PRODUCED USING SAME, AND COMPONENT PRODUCED USING SAID TRANSFER MOLD

Title (de)
HERSTELLUNGSVERFAHREN FÜR EINE PRESSSPRITZFORM, IN DIESEM VERFAHREN HERGESTELLTE PRESSSPRITZFORM SOWIE UNTER VERWENDUNG DIESER PRESSSPRITZFORM HERGESTELLTE KOMPONENTE

Title (fr)
PROCÉDÉ DE PRODUCTION POUR MOULE À TRANSFERT, MOULE À TRANSFERT PRODUIT À L'AIDE DE CELUI-CI ET COMPOSANT PRODUIT À L'AIDE DUDIT MOULE À TRANSFERT

Publication
EP 2781628 A4 20150304 (EN)

Application
EP 11875931 A 20111115

Priority
JP 2011006355 W 20111115

Abstract (en)
[origin: EP2781628A1] A transfer mold, which has superior durability and high aspect ratio, for production of a component by electroplating and a component produced thereby are provided. A method therefor includes the steps of: forming a resist pattern having a shape of a component with a desired aspect ratio on a metal substrate 10, a sidewall of the resist pattern forming a desired angle \pm ; creating a transfer mold by filing up the resist pattern having the shape of the component by electroplating to a predetermined thickness; and providing a master mold 20 by separating the transfer mold from the metal substrate.

IPC 8 full level
C25D 1/10 (2006.01); **C25D 1/00** (2006.01); **C25D 1/20** (2006.01); **C25D 1/22** (2006.01)

CPC (source: EP US)
C25D 1/00 (2013.01 - EP US); **C25D 1/003** (2013.01 - US); **C25D 1/10** (2013.01 - EP US); **C25D 1/20** (2013.01 - EP US); **C25D 1/22** (2013.01 - EP US)

Citation (search report)

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Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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DOCDB simple family (application)
EP 11875931 A 20111115; CN 201180074858 A 20111115; JP 2011006355 W 20111115; JP 2012518642 A 20111115; KR 20147016235 A 20111115; TW 101100392 A 20120105; US 201114358300 A 20111115